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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/811,326	03/26/2004	Frank M. Cerio JR.	TAZ-259	9467
	7590 12/02/200 ON & EVANS, LLP (*	EXAMINER		
2700 CAREW 7	TOWER	MCDONALD, RODNEY GLENN		
441 VINE STR CINCINNATI,			ART UNIT	PAPER NUMBER
			1795	
			NOTIFICATION DATE	DELIVERY MODE
			12/02/2009	ELECTRONIC

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

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Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)		
10/811,326	CERIO ET AL.		
Examiner	Art Unit		
Rodney G. McDonald	1795		

	Rodney G. McDonald	1795	
The MAILING DATE of this communication appe	ars on the cover sheet with the o	correspondence add	ress
THE REPLY FILED <u>28 October 2009</u> FAILS TO PLACE THIS A		-	
1. The reply was filed after a final rejection, but prior to or on application, applicant must timely file one of the following application in condition for allowance; (2) a Notice of Appelor Continued Examination (RCE) in compliance with 37 C periods:	the same day as filing a Notice of a replies: (1) an amendment, affidavi eal (with appeal fee) in compliance	Appeal. To avoid abar t, or other evidence, w with 37 CFR 41.31; or	hich places the (3) a Request
a) The period for reply expires <u>4</u> months from the mailing date	of the final rejection.		
b) The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire la Examiner Note: If box 1 is checked, check either box (a) or (MONTHS OF THE FINAL REJECTION. See MPEP 706.07(dvisory Action, or (2) the date set forth ater than SIX MONTHS from the mailing b). ONLY CHECK BOX (b) WHEN THE	g date of the final rejection	n.
Extensions of time may be obtained under 37 CFR 1.136(a). The date have been filed is the date for purposes of determining the period of extunder 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b).	ension and the corresponding amount hortened statutory period for reply origi than three months after the mailing dat	of the fee. The appropria nally set in the final Offic	ate extension fee e action; or (2) as
2. The Notice of Appeal was filed on A brief in comp filing the Notice of Appeal (37 CFR 41.37(a)), or any exter Notice of Appeal has been filed, any reply must be filed was AMENDMENTS	nsion thereof (37 CFR 41.37(e)), to	avoid dismissal of the	
3. The proposed amendment(s) filed after a final rejection, be	out prior to the date of filing a brief	will not be entered be	Called
(a) They raise new issues that would require further cor			cause
(b) ☐ They raise the issue of new matter (see NOTE belo			
(c) ☐ They are not deemed to place the application in bet appeal; and/or	ter form for appeal by materially red	ducing or simplifying th	ne issues for
(d) They present additional claims without canceling a €	corresponding number of finally reje	ected claims.	
NOTE: (See 37 CFR 1.116 and 41.33(a)).			
4. The amendments are not in compliance with 37 CFR 1.12	21. See attached Notice of Non-Co	mpliant Amendment (I	PTOL-324).
5. Applicant's reply has overcome the following rejection(s):			
 Newly proposed or amended claim(s) would be all non-allowable claim(s). 	owable if submitted in a separate, t	timely filed amendmer	nt canceling the
7. For purposes of appeal, the proposed amendment(s): a) I how the new or amended claims would be rejected is prov. The status of the claim(s) is (or will be) as follows:		l be entered and an ex	xplanation of
Claim(s) allowed:			
Claim(s) objected to: Claim(s) rejected: <u>32,33 and 94</u> .			
Claim(s) withdrawn from consideration:			
AFFIDAVIT OR OTHER EVIDENCE			
 The affidavit or other evidence filed after a final action, bu because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e). 	sufficient reasons why the affidavi	it or other evidence is	necessary and
 The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to o showing a good and sufficient reasons why it is necessary 	vercome <u>all</u> rejections under appea	al and/or appellant fails	s to provide a
10. ☐ The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER	n of the status of the claims after er	ntry is below or attache	ed.
 The request for reconsideration has been considered bu <u>See Continuation Sheet.</u> 	t does NOT place the application in	condition for allowand	ce because:
12. Note the attached Information <i>Disclosure Statement</i> (s). (13. Other:	PTO/SB/08) Paper No(s)		
	/Rodney G. McDonald/ Primary Examiner, Art U	Init 1795	

Continuation of 11. does NOT place the application in condition for allowance because: of the reasons set forth in the final rejection. Specifically the amended claims require repairing a barrier layer (Claim 32), depositing a barrier layer (Claim 33) and depositing a seed layer (Claim 94). The prior art of record shows simultaneously depositing and etching to repair a seed layer and to deposit metal films. Yao et al. specifically states that the material can be any conductive material for depositing. Yasar et al. teach that barrier layers can be deposited. Therefore one of ordinary skill in the art would readily modify Yao et al. by ending deposition to deposit barrier layers as taught by Yasar et al. since both references require depositing conducting material for semiconductor manufacture. Yao et al. teach depositing copper as a layer as such the copper layer can act as a seed layer for example Fig. 3B layer 50. Depending on whether the deposition is continued the hole can be filled. However if the deposition is ended the result in Fig. 3B can be achieved.